

**4-PIN SOP LOW OFF-STATE LEAKAGE CURRENT
1-ch Optical Coupled MOS FET**

-NEPOC Series-

DESCRIPTION

The PS7200U-1A is a low output capacitance solid state relay containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control, due to its extremely low off-state leakage current, low output capacitance, and high-speed turn-on time.

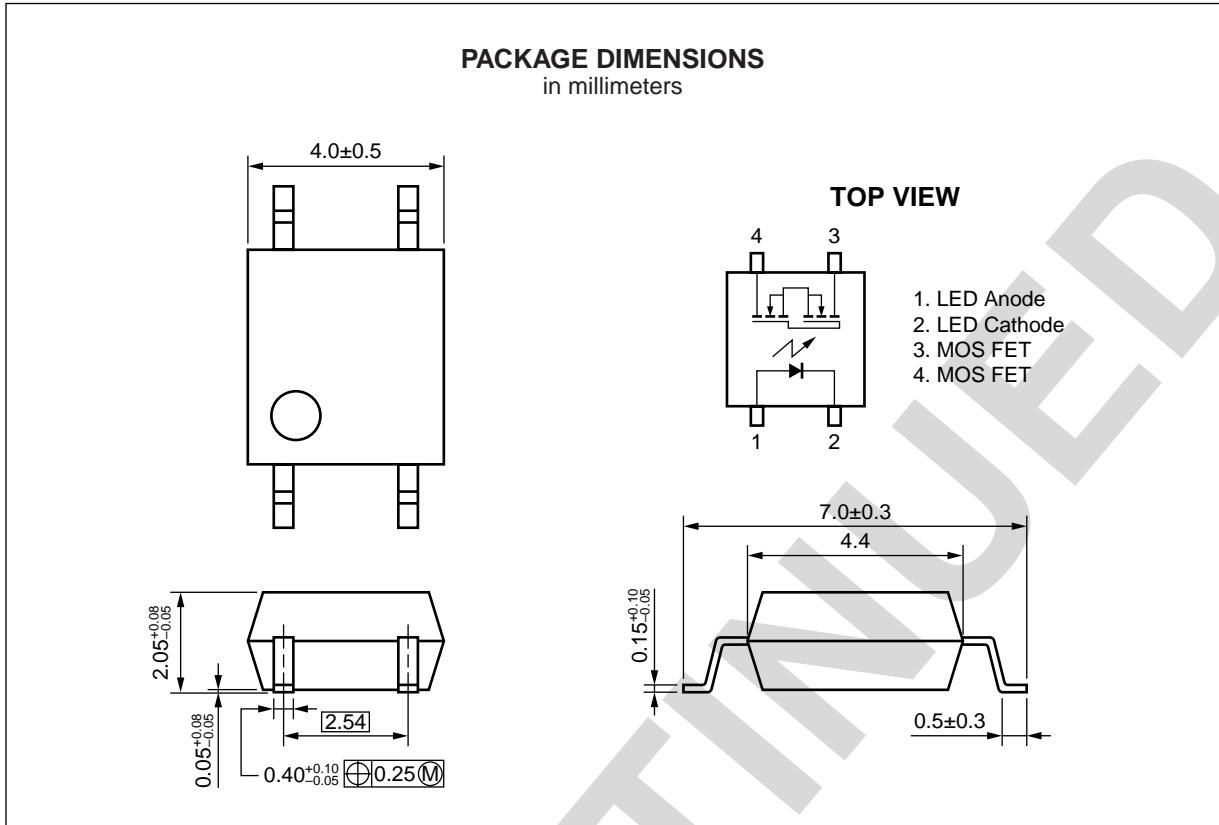
FEATURES

- Low off-state leakage current ($I_{Loff} = 0.1 \text{ nA TYP.}$)
- Break down voltage ($V_L = 80 \text{ V}$)
- High-speed turn-on time ($t_{on} = 0.05 \text{ ms TYP.}$)
- Low output capacitance ($C_{out} = 2.3 \text{ pF TYP.}$)
- $C \times R$ ($C \times R = 40 \text{ pF} \cdot \Omega$)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- Low offset voltage
- Ordering number of taping product : PS7200U-1A-E3, E4: 900 pcs/reel
: PS7200U-1A-F3, F4: 3 500 pcs/reel
- Pb-Free product

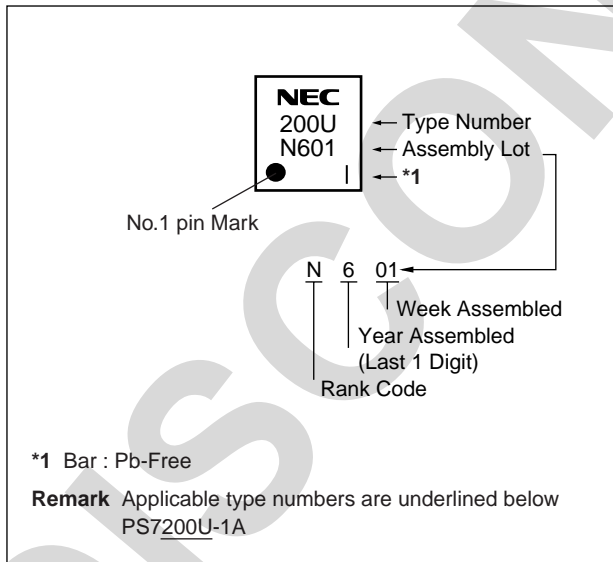
APPLICATIONS

- Measurement equipment

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.



<R> **MARKING EXAMPLE (LASER MARKING)**



<R> **ORDERING INFORMATION**

| Part Number | Order Number | Solder Plating Specification | Packing Style |
|---------------|-----------------|------------------------------|------------------------------|
| PS7200U-1A | PS7200U-1A-A | Pb-Free | Magazine case 100 pcs |
| PS7200U-1A-E3 | PS7200U-1A-E3-A | | Embossed Tape 900 pcs/reel |
| PS7200U-1A-E4 | PS7200U-1A-E4-A | | |
| PS7200U-1A-F3 | PS7200U-1A-F3-A | | Embossed Tape 3 500 pcs/reel |
| PS7200U-1A-F4 | PS7200U-1A-F4-A | | |

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

| Parameter | | Symbol | Ratings | Unit |
|-------------------------------|---|------------------|-------------|---------|
| Diode | Forward Current (DC) | I _F | 50 | mA |
| | Reverse Voltage | V _R | 5.0 | V |
| | Power Dissipation | P _D | 50 | mW |
| | Peak Forward Current *1 | I _{FP} | 1 | A |
| MOS FET | Break Down Voltage | V _L | 80 | V |
| | Continuous Load Current | I _L | 40 | mA |
| | Pulse Load Current *2 (AC/DC Connection) | I _{LP} | 80 | mA |
| | Power Dissipation | P _D | 300 | mW |
| Isolation Voltage *3 | | BV | 1 500 | Vr.m.s. |
| Total Power Dissipation | | P _T | 350 | mW |
| Operating Ambient Temperature | | T _A | -40 to +85 | °C |
| Storage Temperature | | T _{stg} | -40 to +100 | °C |

*1 PW = 100 μs, Duty Cycle = 1%

*2 PW = 100 ms, 1 shot

*3 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.
Pins 1-2 shorted together, 3-4 shorted together.

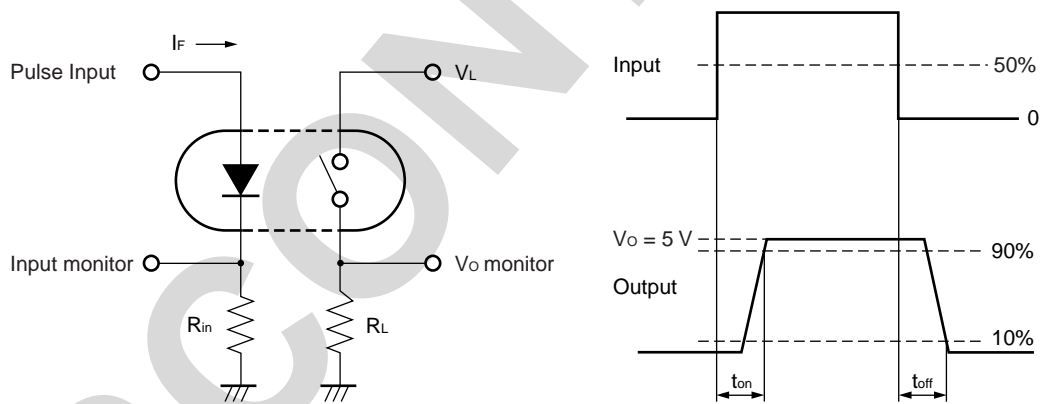
RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

| Parameter | Symbol | MIN. | TYP. | MAX. | Unit |
|-----------------------|----------------|------|------|------|------|
| LED Operating Current | I _F | 2 | 10 | 20 | mA |
| LED Off Voltage | V _F | 0 | | 0.5 | V |

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

| Parameter | | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|-----------|-------------------------------|-------------------|--|-----------------|------|------|------|
| Diode | Forward Voltage | V _F | I _F = 5 mA | | 1.1 | 1.3 | V |
| | Reverse Current | I _R | V _R = 5 V | | 0.01 | 5.0 | μA |
| MOS FET | Off-state Leakage Current | I _{Loff} | V _D = 80 V | | 0.1 | 1.0 | nA |
| | Output Capacitance | C _{out} | V _D = 0 V, f = 1 MHz | | 2.3 | 3.5 | pF |
| Coupled | LED On-state Current | I _{Fon} | I _L = ±40 mA | | | 2.0 | mA |
| | On-state Resistance | R _{on} | I _F = 5 mA, I _L = ±40 mA | | 17 | 25 | Ω |
| | Turn-on Time ^{*1,2} | t _{on} | I _F = 5 mA, V _L = 5 V, R _L = 500 Ω, | | 0.05 | 0.5 | ms |
| | Turn-off Time ^{*1,2} | t _{off} | PW ≥ 0.5 ms | | 0.15 | 0.5 | |
| | Isolation Resistance | R _{I-O} | V _{I-O} = 1.0 kV _{DC} | 10 ⁹ | | | Ω |
| | Isolation Capacitance | C _{I-O} | V = 0 V, f = 1 MHz | | 0.3 | | pF |

*1 Test Circuit for Switching Time



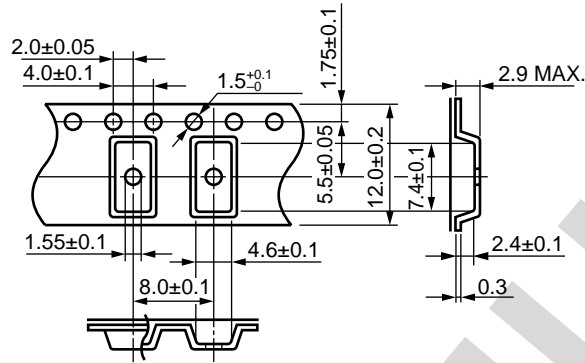
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*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 0.5 ms.

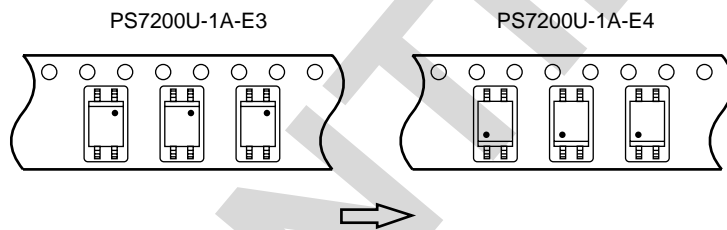
Be aware that when the device operates with an input-pulse width less than 0.5 ms, the turn-on time and turn-off time will increase.

TAPING SPECIFICATIONS (in millimeters)

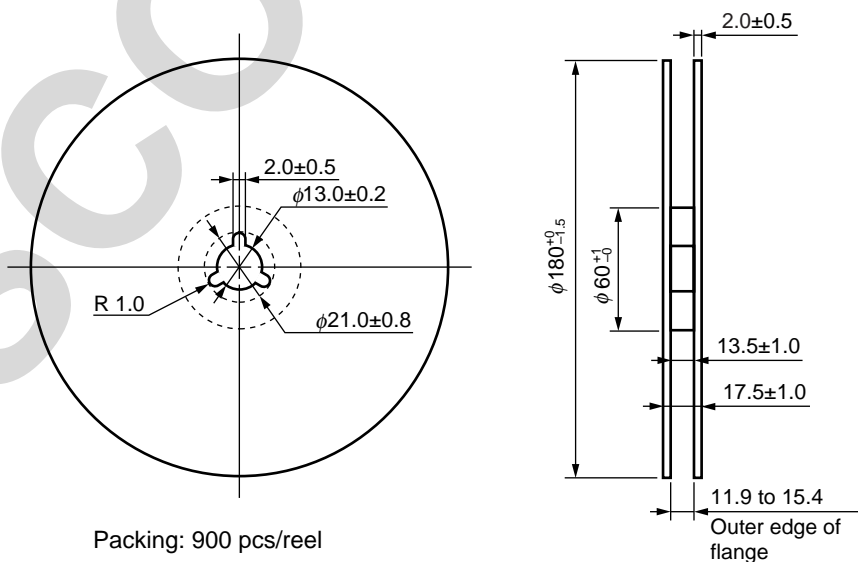
Outline and Dimensions (Tape)



Tape Direction

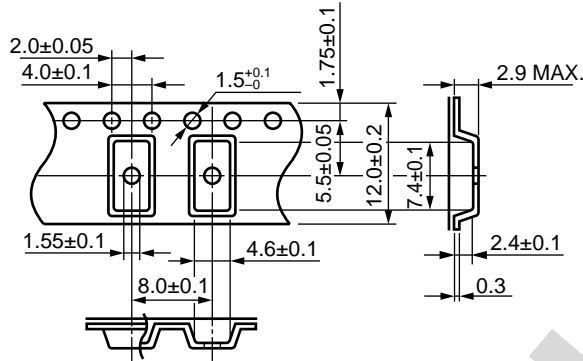


Outline and Dimensions (Reel)

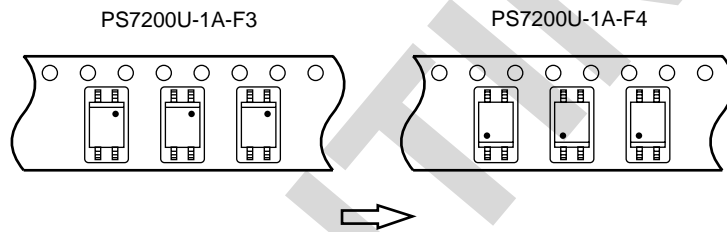


Packing: 900 pcs/reel

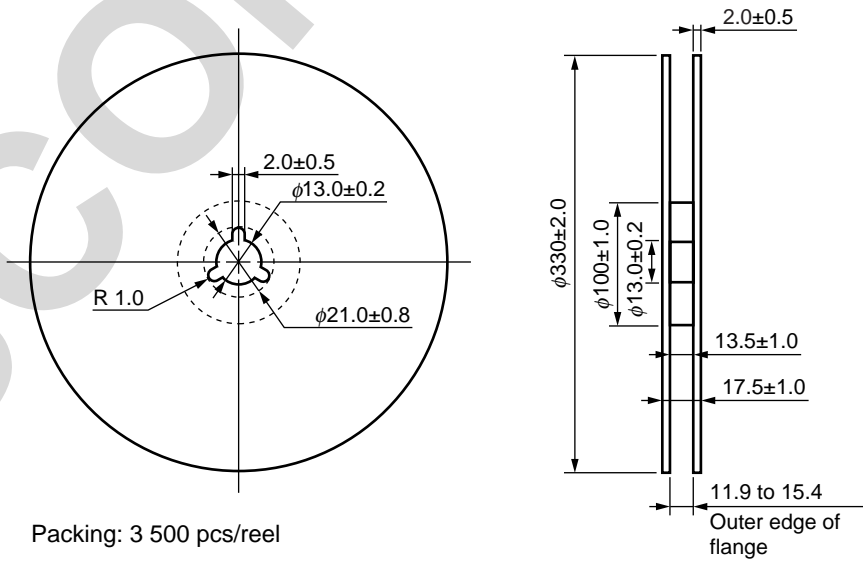
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



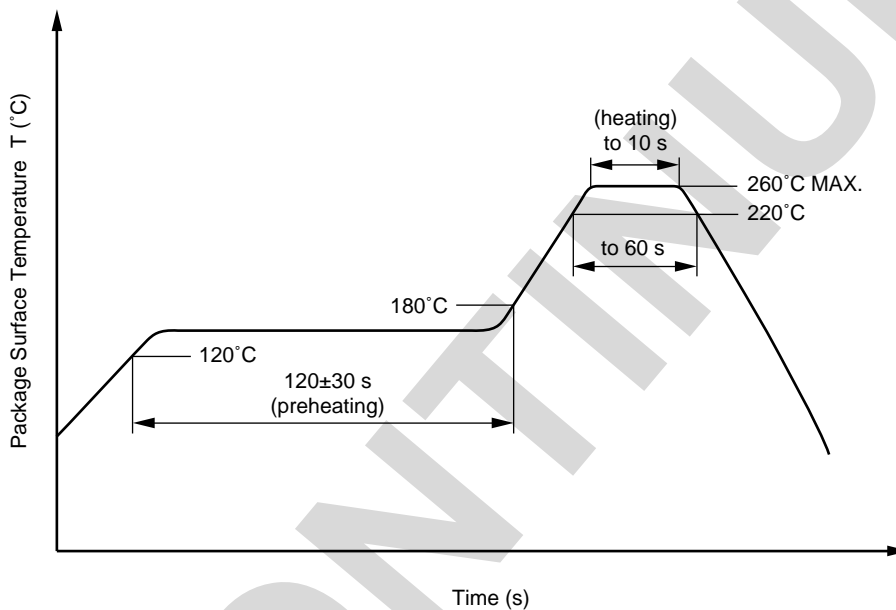
Packing: 3 500 pcs/reel

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

DISCONTINUED

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| | | |
|-----------------------|----------------------|---|
| <p>Caution</p> | <p>GaAs Products</p> | <p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. <ol style="list-style-type: none"> 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth. |
|-----------------------|----------------------|---|

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